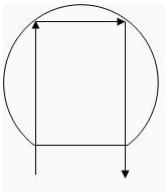
Part Number	Customer

Category		Parameter	Specification	Measurement Method
OverallWafer	1.0	Diameter	100.00 +/- 0.50 mm	
	2.0	Primary Flat Orientation	<110> +/- 1 degree	Wafer Vendor
	3.0	Primary Flat Length	32.50 +/- 2.50 mm	Wafer Vendor
	4.0	Secondary Flat Orientation	none/semi std	
	5.0	Overall Thickness	510.00 +/- 7.00 µm	ADE 100%
	6.0	Total Thickness Variation (TTV)	<5.00µm	Guaranteed by Process
	7.0	Bow	<60.00µm	ADE to ASTM F534, 20%
	8.0	Warp	<60.00µm	ADE to ASTM F657, 20%
	9.0	Edge Chips	0	Bright Light, 100% (note 2)
	10.0	Edge Exclusion	5mm	
HandleSilicon	11.0	Handle Growth Method	CZ	Wafer Vendor - Topsil only
	12.0	Handle Orientation	{111} off 2.5 +/- 0.5 degree	Wafer Vendor
	13.0	Handle Thickness	415.00 +/- 5.00 µm	ADE, 100%
	14.0	Handle Doping Type	N	Wafer Vendor
	15.0	Handle Dopant	Arsenic	Wafer Vendor
	16.0	Handle Resistivity	<0.003 Ohmcm	Wafer Vendor
	17.0	Backside Finish	Lapped and etched with lasermark and no oxide.	Wafer Vendor
DeviceSilicon	21.0	Device Growth Method	FZ	Wafer Vendor - Topsil only
	22.0	Device Orientation	{111} off 3.5 +/- 0.5 degree	Wafer Vendor
	23.0	Nominal Thickness	95.00 +/- 2.00 µm	Filmetrics F50 XT, 100% 9-Pt (note3)
	24.0	Distance to device silicon edge from wafer edge	< 2 mm	Guaranteed by Process
	25.0	Device Doping Type	N	Wafer Vendor
	26.0	Device Dopant	Phosphorous	Wafer Vendor
	27.0	Device Resistivity	> 5000 Ohm-cm	Wafer Vendor
	28.0	Buried Layer Implant	none	implant vendor
	29.0	Voids	0	Bright Light, 100% (note 2)
	30.0	Scratches	0	Bright Light, 100% (note 2)
	31.0	Haze	none	Bright Light, 100% (note 2)

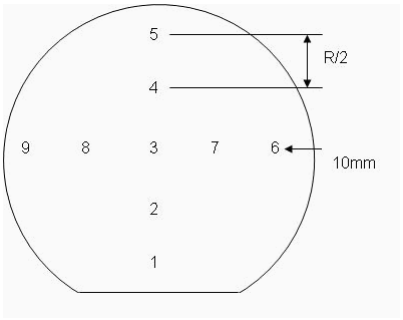
Part Number	Customer

Category	Parameter	Specification	Measurement Method
Shipping Details	Wafer per box :	Max 25	
	Packaging :	Taped Polypropylene Wafer Box Empak, Ultrapak, 100.00mm Antistatic Double Bagging	
	Lot Shipment Data	Device Thickness Bow / Warp Data Handle and SOI Thickness	
Explanatory Notes	1. Microscope inspection performed using microscope scan as below. 5x objective.		



2. All bright light inspections performed exclude all wafer area outside the edge exclusion defined in Overall Wafer, Edge Exclusion. High intensity bright lamp inspection as per ASTM F523.

3. 9 point measurement are as shown in the diagram below:



Additional Information